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# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

PUBLICATION NUMBER : 2000091602  
PUBLICATION DATE : 31-03-00

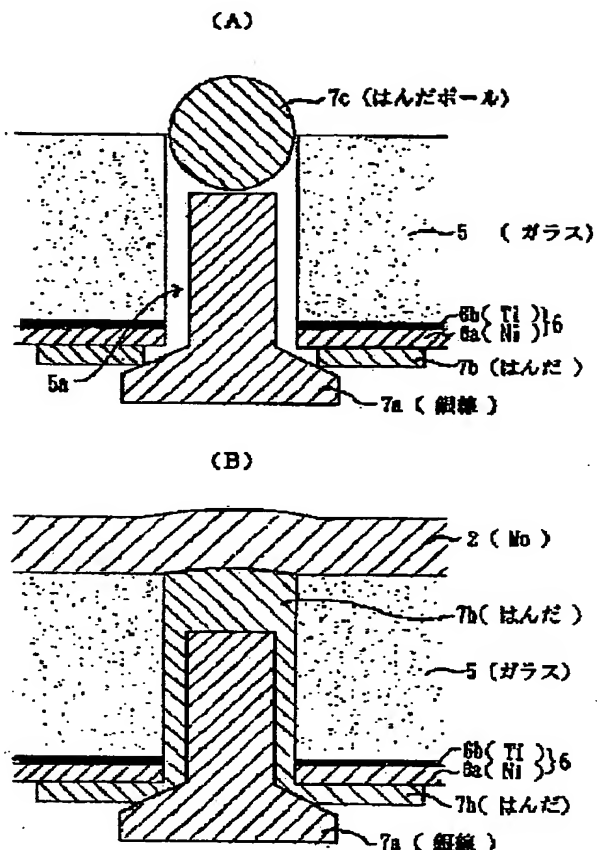
APPLICATION DATE : 07-09-98  
APPLICATION NUMBER : 10268963

APPLICANT : HONDA MOTOR CO LTD;

INVENTOR : INABA ATSUSHI;

INT.CL. : H01L 31/04

TITLE : METHOD FOR EXTRACTING  
ELECTRODE OF SOLAR BATTERY



**ABSTRACT :** PROBLEM TO BE SOLVED: To provide a method for extracting the electrode of a solar battery for reducing the resistance of an electrode and loss by Joule's heat and for enhancing photoelectric transfer efficiency.

**SOLUTION:** This solar battery is provided with an insulating substrate 5, lower electrode layer 2 made of molybdenum formed on the surface of the insulating substrate as materials, semiconductor photoelectric transfer layer made of Cu, In, Ga, and Se or the like formed on the surface of the lower electrode layer as main components, and transparent upper electrode layer formed on the surface of this semiconductor photoelectric transfer layer. Then, this method for extracting an electrode comprises a process for forming an auxiliary electrode layer 6 on the back face of the insulating substrate 5 prior to the formation of the lower electrode layer 2 on the surface of the insulating substrate 5, process for forming a through-hole 5a through the insulating substrate, and process for forming a conductive path 7 including at least a solder layer for connecting the lower electrode layer 2 with the auxiliary electrode layer 6 on the back face of the substrate inside the through-hole 5a.

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